



Click [here](#) for the 3D model.

Dimensions	
Chip Size	0603
L	1.6mm +0.2/-0.15mm (0.063 in +0.008/-0.006 in)
W	0.81mm +0.2/-0.15mm (0.032 in +0.008/-0.006 in)
T	1.02mm MAX (0.04 in MAX)
B	0.41mm +/-0.2mm (0.016 in +/-0.008 in)

  

Packaging Specifications	
Packaging	Waffle
Packaging Quantity	368

General Information	
Series	SMD MIL COG PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	No
Prop 65	<b>⚠ WARNING:</b> Cancer and reproductive harm - <a href="http://www.p65warnings.ca.gov">http://www.p65warnings.ca.gov</a> .
Termination	Solder Plated
Failure Rate	N/A
Qualifications	MIL-PRF-32535 T-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	100 pF
Capacitance Tolerance	10%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Dissipation Factor	0.15% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)